APS01-002B

OTPE 4707 W

Serial No. 10/826,752

The

October 8, 2007

To: Commissioner to Butterns

P.O. Box 1450 Alexandria, VA 22313-1450

Fr:

Stephen B. Ackerman, Reg. No. 37,761

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

Serial No.

10/826,752

04/16/04

ROMEO EMMANUEL P. ALVAREZ

"METHOD FOR FORMING A WAFER LEVEL CHIP SCALE PACKAGE, AND PACKAGE FORMED THEREBY"

Grp. Art Unit: 2813

JAMES M. MITCHELL

RESPONSE TO NOTICE OF NON-COMPLIANCE

Dear Sir:

In response to the Notice of Non-Compliance and the Final Office Action dated January 26, 2007, please consider the remarks concerning the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on 1450, 2007.

Stephen B. Ackerman, Rep. No. 37,761

Signature __

Date 10 15 07